

INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

ATTY DOCKET NO.

41890-00990

SERIAL NO.

09/698,363

APPLICANT(S)

Kodas et al.

FILING DATE

10/27/00

GROUP

1714

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
JP	1.	3,620,714	11/16/71	Short	75	.5	
	2.	3,717,481	02/20/73	Short	106	1	
	3.	3,725,035	04/03/73	Short et al.	75	.5	
	4.	3,768,994	10/30/73	Daiga	75	.5	
	5.	3,816,097	06/11/74	Daiga	75	.5	
	6.	3,885,955	05/27/75	Lutz et al.	75	.5	
	7.	3,966,463	06/29/76	Fraioli et al.	75	108	
	8.	4,020,206	04/26/77	Beil	428	137	
	9.	4,023,961	05/17/77	Douglas et al.	75	.5	
	10.	4,036,634	07/19/77	Fraioli et al.	75	.5	
JP	11.	4,274,877	06/23/81	Collier et al.	75	252	

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FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

JP	25.	Fievet et al., "Preparing Monodisperse Metal Powders in Micrometer and Submicrometer Sizes by the Polyol Process", MRS Bulletin, pp. 29-34, December 1989.
JP	26.	Getty et al., "High Performance Thick Film Gold Conductors", International Journal for Hybrid Microelectronics, Vol. 5, No. 2, pp. 487-495, November 1982.

EXAMINER

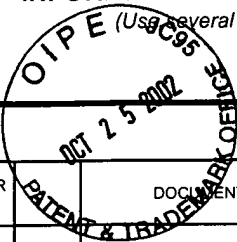
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*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
PN	12. 4,326,889	04/27/82	Sperner	106	35	
	13. 4,410,457	10/18/83	Fujimura et al.	252	508	
	14. 4,477,296	10/16/84	Nair	148	6.14	
	15. 4,731,110	03/15/88	Kopatz et al.	75	.5	
	16. 4,804,167	02/14/89	Kock et al.	266	200	
	17. 4,897,110	01/30/90	Kock et al.	75	.5	
	18. 4,954,926	09/04/90	Pepin	361	304	
	19. 5,039,552	08/13/91	Riemer	427	96	
	20. 5,126,915	06/30/92	Pepin et al.	361	304	
	21. 5,167,869	12/01/92	Nebe et al.	252	514	
PN	22. 5,283,104	02/01/94	Aoude et al.	428	195	

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						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

PN	27.	Majumdar et al., "Gold Particle Generation by Spray Pyrolysis", Adv. Mater., Vol. 8, No. 12., pp. 1020-1022, 1996.
PN	28.	Seshadri et al., "Preparation of Monodispersed, Submicron Gold Particles", Materials Research Bulletin, Vol. 29, No. 7, pp. 795-799, 1994

EXAMINER

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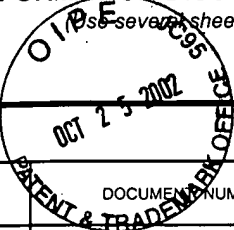
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U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
PM	23. 5,429,670	07/04/95	Miyoshi	106	1.18	
PM	24. 5,616,165	04/01/97	Glicksman et al.	75	369	

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						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

PM	30.	Silvert et al., "Synthesis of Monodisperse Submicronic Gold Particles by the Polyol Process", Solid State Ionics, Vol. 82, pp. 53-60, 1995

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